

BLS6G2731S-130

LDMOS S-band radar power transistor

Rev. 2 — 18 November 2010

Product data sheet

1. Product profile

1.1 General description

130 W LDMOS power transistor intended for radar applications in the 2.7 GHz to 3.1 GHz range.

Table 1. Typical performance

Typical RF performance at $T_{case} = 25\text{ °C}$; $t_p = 300\text{ }\mu\text{s}$; $\delta = 10\%$; $I_{Dq} = 100\text{ mA}$; in a class-AB production test circuit.

Mode of operation	f (GHz)	V _{DS} (V)	P _L (W)	G _p (dB)	η_D (%)	t _r (ns)	t _f (ns)
pulsed RF	2.7 to 3.1	32	130	12	50	20	6

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

1.2 Features and benefits

- Typical pulsed RF performance at a frequency of 2.7 GHz to 3.1 GHz, a supply voltage of 32 V, an I_{Dq} of 100 mA, a t_p of 300 μs with δ of 10 %:
 - ◆ Output power = 130 W
 - ◆ Power gain = 12 dB
 - ◆ Efficiency = 50 %
- Easy power control
- Integrated ESD protection
- High flexibility with respect to pulse formats
- Excellent ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (2.7 GHz to 3.1 GHz)
- Internally matched for ease of use
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

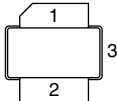
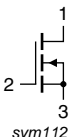
1.3 Applications

- S-band power amplifiers for radar applications in the 2.7 GHz to 3.1 GHz frequency range



2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	drain		 sym112
2	gate		
3	source		

[1] Connected to flange.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BLS6G2731S-130	-	ceramic earless flanged cavity package; 2 leads	SOT922-1

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Min	Max	Unit
V_{DS}	drain-source voltage	-	60	V
V_{GS}	gate-source voltage	-0.5	+13	V
I_D	drain current	-	33	A
T_{stg}	storage temperature	-65	+150	°C
T_j	junction temperature	-	200	°C

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$Z_{th(j-mb)}$	transient thermal impedance from junction to mounting base	$T_{case} = 85\text{ °C}; P_L = 130\text{ W}$		
		$t_p = 100\text{ }\mu\text{s}; \delta = 10\text{ %}$	0.23	K/W
		$t_p = 200\text{ }\mu\text{s}; \delta = 10\text{ %}$	0.28	K/W
		$t_p = 300\text{ }\mu\text{s}; \delta = 10\text{ %}$	0.32	K/W
		$t_p = 100\text{ }\mu\text{s}; \delta = 20\text{ %}$	0.33	K/W

6. Characteristics

Table 6. Characteristics

$T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 0.6\text{ mA}$	60	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 180\text{ mA}$	1.4	1.8	2.4	V
I_{DSS}	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 28\text{ V}$	-	-	4.2	μA
I_{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; V_{DS} = 10\text{ V}$	27	33	-	A
I_{GSS}	gate leakage current	$V_{GS} = 11\text{ V}; V_{DS} = 0\text{ V}$	-	-	450	nA
g_{fs}	forward transconductance	$V_{DS} = 10\text{ V}; I_D = 9\text{ A}$	8.1	13	-	S
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; I_D = 6.3\text{ A}$	-	0.085	0.135	Ω

7. Application information

Table 7. Application information

Mode of operation: pulsed RF; $t_p = 300\text{ }\mu\text{s}$; $\delta = 10\text{ }\%$; RF performance at $V_{DS} = 32\text{ V}$; $I_{Dq} = 100\text{ mA}$; $T_{case} = 25\text{ }^\circ\text{C}$; unless otherwise specified, in a class-AB production circuit.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
P_L	output power		-	130	-	W
V_{DD}	supply voltage	$P_L = 130\text{ W}$	-	-	32	V
G_p	power gain	$P_L = 130\text{ W}$	10	12	-	dB
RL_{in}	input return loss	$P_L = 130\text{ W}$	5.5	8	-	dB
$P_{L(1dB)}$	output power at 1 dB gain compression		-	140	-	W
η_D	drain efficiency	$P_L = 130\text{ W}$	45	50	-	%
$P_{droop(pulse)}$	pulse droop power	$P_L = 130\text{ W}$	-	0	0.25	dB
t_r	rise time	$P_L = 130\text{ W}$	-	20	50	ns
t_f	fall time	$P_L = 130\text{ W}$	-	6	50	ns

Table 8. Typical impedance

f (GHz)	Z_S (Ω)	Z_L (Ω)
2.7	3.2 – j6.5	4.5 – j3.6
2.8	4.4 – j6.2	3.5 – j3.8
2.9	5.6 – j7.3	3.7 – j3.1
3.0	4.9 – j9.2	3.0 – j3.3
3.1	3 – j9.5	2.8 – j3.6

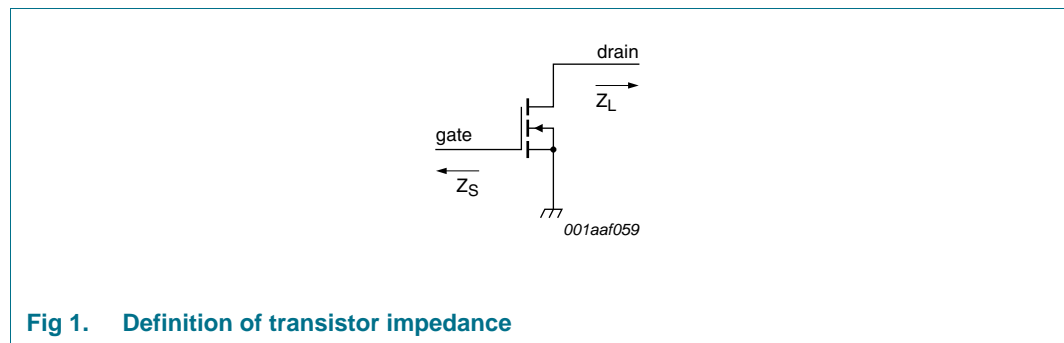
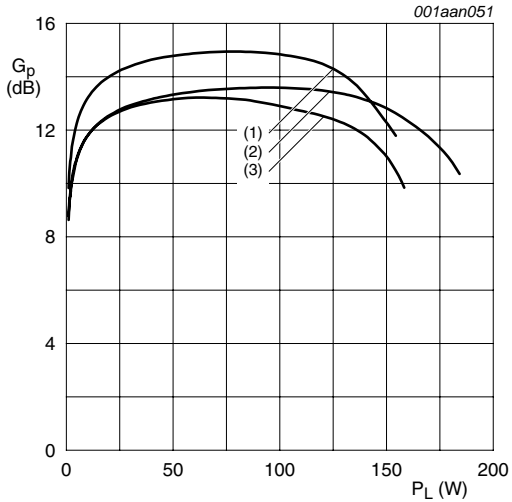


Fig 1. Definition of transistor impedance

7.1 Ruggedness in class-AB operation

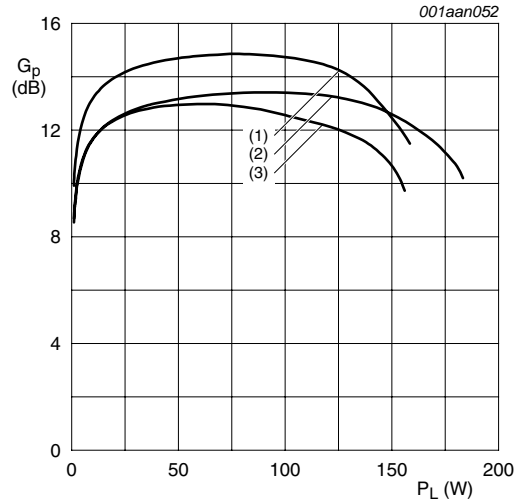
The BLS6G2731S-130 is capable of withstanding a load mismatch corresponding to VSWR = 5 : 1 through all phases under the following conditions: $V_{DS} = 32\text{ V}$; $I_{DQ} = 100\text{ mA}$; $P_L = 130\text{ W}$; $t_p = 300\text{ }\mu\text{s}$; $\delta = 10\text{ }\%$.

7.2 Graphs



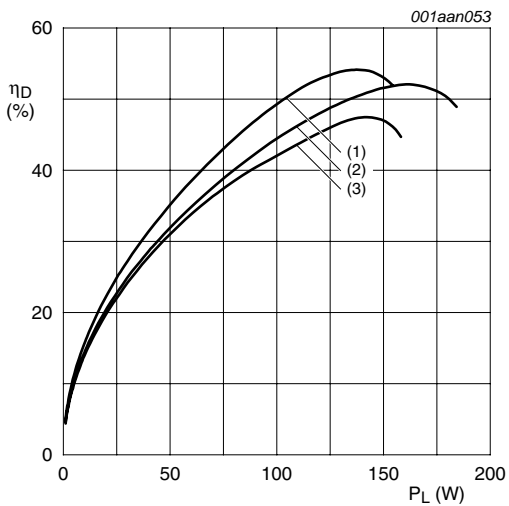
$V_{DS} = 32\text{ V}; I_{Dq} = 100\text{ mA}; t_p = 300\text{ }\mu\text{s}; \delta = 10\text{ }\%$.
 (1) $f = 2.7\text{ GHz}$
 (2) $f = 2.9\text{ GHz}$
 (3) $f = 3.1\text{ GHz}$

Fig 2. Power gain as a function of load power; typical values



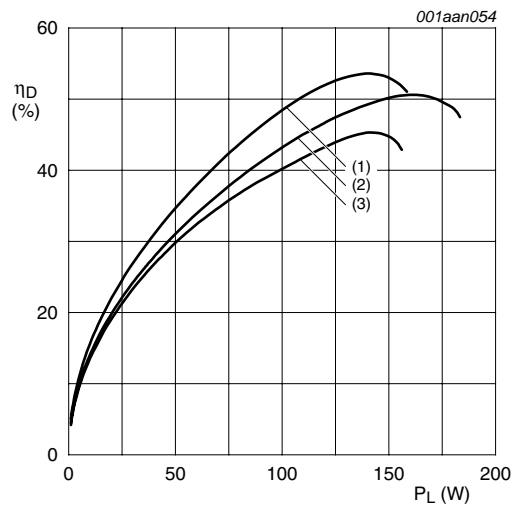
$V_{DS} = 32\text{ V}; I_{Dq} = 100\text{ mA}; t_p = 100\text{ }\mu\text{s}; \delta = 20\text{ }\%$.
 (1) $f = 2.7\text{ GHz}$
 (2) $f = 2.9\text{ GHz}$
 (3) $f = 3.1\text{ GHz}$

Fig 3. Power gain as a function of load power; typical values



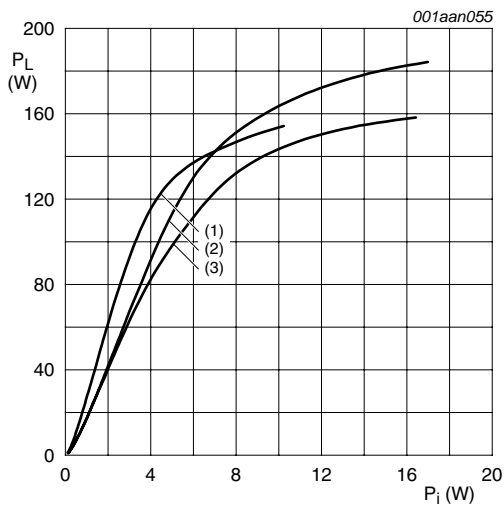
$V_{DS} = 32\text{ V}; I_{Dq} = 100\text{ mA}; t_p = 300\text{ }\mu\text{s}; \delta = 10\text{ }\%$.
 (1) $f = 2.7\text{ GHz}$
 (2) $f = 2.9\text{ GHz}$
 (3) $f = 3.1\text{ GHz}$

Fig 4. Drain efficiency as a function of load power; typical values



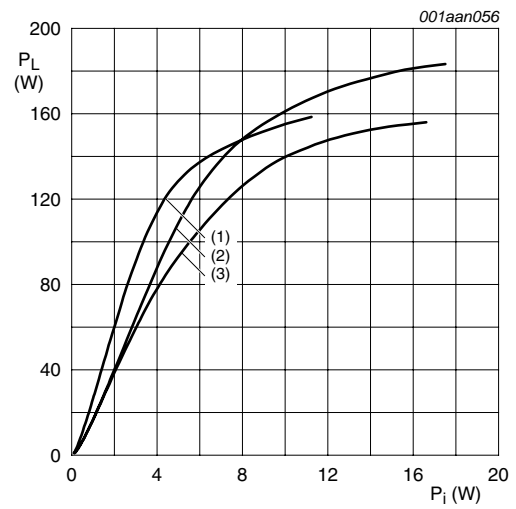
$V_{DS} = 32\text{ V}; I_{Dq} = 100\text{ mA}; t_p = 100\text{ }\mu\text{s}; \delta = 20\text{ }\%$.
 (1) $f = 2.7\text{ GHz}$
 (2) $f = 2.9\text{ GHz}$
 (3) $f = 3.1\text{ GHz}$

Fig 5. Drain efficiency as a function of load power; typical values



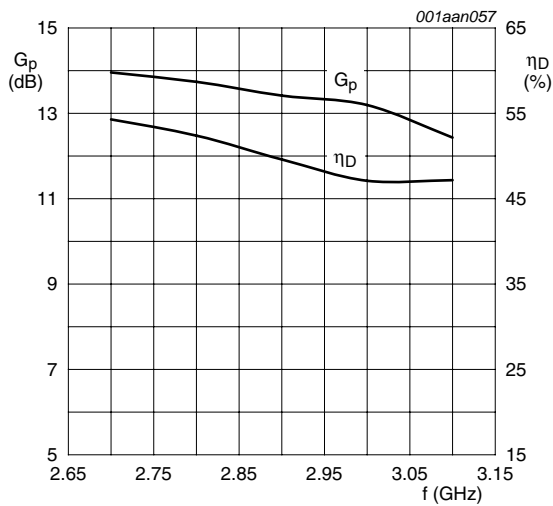
$V_{DS} = 32\text{ V}; I_{DQ} = 100\text{ mA}; t_p = 300\text{ }\mu\text{s}; \delta = 10\text{ }\%$.
 (1) $f = 2.7\text{ GHz}$
 (2) $f = 2.9\text{ GHz}$
 (3) $f = 3.1\text{ GHz}$

Fig 6. Load power as a function of input power; typical values



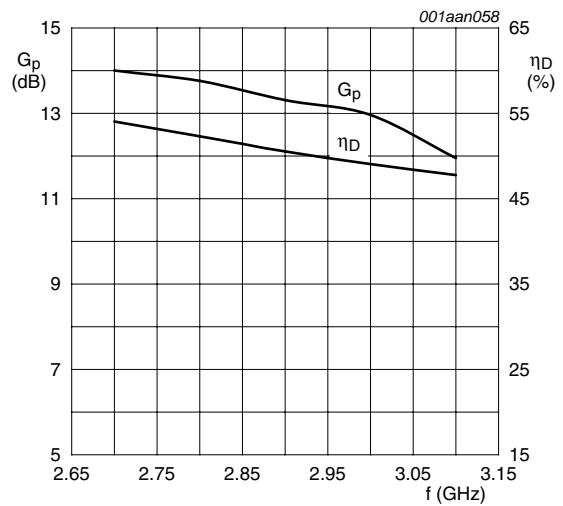
$V_{DS} = 32\text{ V}; I_{DQ} = 100\text{ mA}; t_p = 100\text{ }\mu\text{s}; \delta = 20\text{ }\%$.
 (1) $f = 2.7\text{ GHz}$
 (2) $f = 2.9\text{ GHz}$
 (3) $f = 3.1\text{ GHz}$

Fig 7. Load power as a function of input power; typical values



$P_L = 130\text{ W}; V_{DS} = 32\text{ V}; I_{DQ} = 100\text{ mA}; t_p = 300\text{ }\mu\text{s}; \delta = 10\text{ }\%$.

Fig 8. Power gain and drain efficiency as function of frequency; typical values



$P_L = 130\text{ W}; V_{DS} = 32\text{ V}; I_{DQ} = 100\text{ mA}; t_p = 100\text{ }\mu\text{s}; \delta = 20\text{ }\%$.

Fig 9. Power gain and drain efficiency as function of frequency; typical values

8. Test information

Table 9. List of components

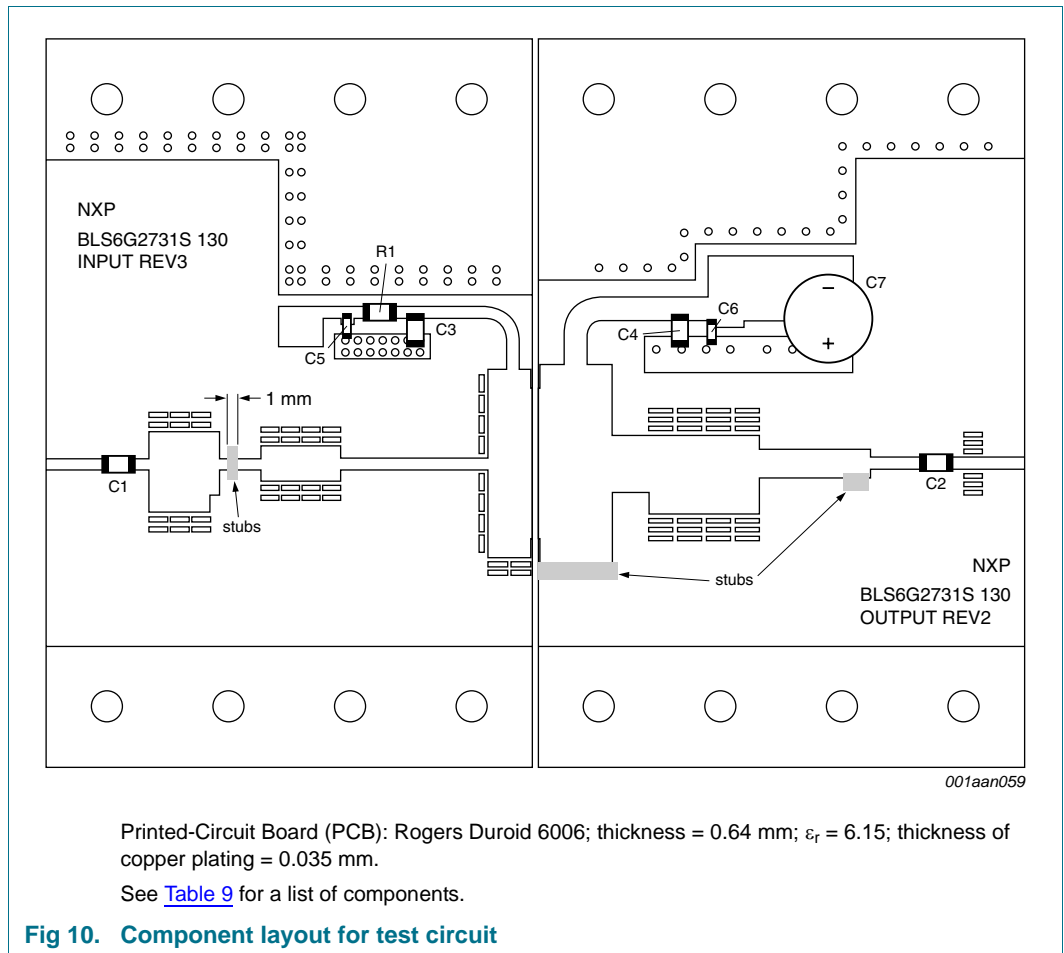
Printed-Circuit Board (PCB): Rogers Duroid 6006; thickness = 0.64 mm; $\epsilon_r = 6.15$; thickness of copper plating = 0.035 mm.

For test circuit see [Figure 10](#).

Component	Description	Value	Remarks
C1, C2, C3, C4	multilayer ceramic chip capacitor	20 pF	[1]
C5, C6	multilayer ceramic chip capacitor	1 nF	[2]
C7	electrolytic capacitor	470 μ F; 63 V	
R1	SMD resistor	10 Ω	

[1] American Technical Ceramics type 100A or capacitor of same quality.

[2] American Technical Ceramics type 700A or capacitor of same quality.



9. Package outline

Ceramic earless flanged cavity package; 2 leads

SOT922-1

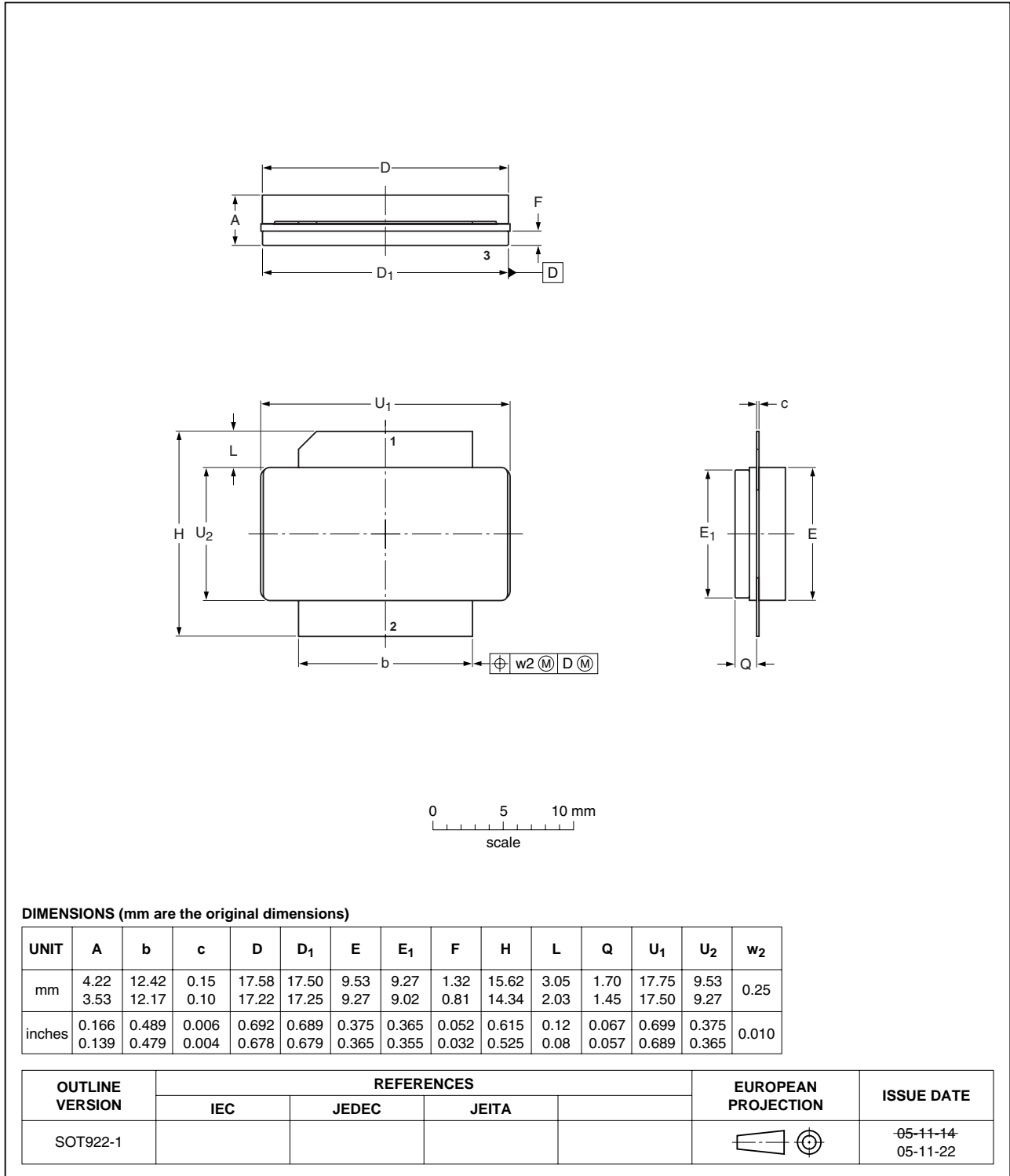


Fig 11. Package outline SOT922-1

10. Abbreviations

Table 10. Abbreviations

Acronym	Description
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
RF	Radio Frequency
VSWR	Voltage Standing-Wave Ratio

11. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLS6G2731S-130 v.2	20101118	Product data sheet	-	BLS6G2731S-130 v.1
Modifications:	<ul style="list-style-type: none"> • Table 1 on page 1: Some values have been changed. • Section 1.2 on page 1: The value of G_p has been changed. • Table 7 on page 3: Some values have been changed. • Table 8 on page 4: Values have been entered. • Section 7.2 on page 5: Section with graphs has been added. • Section 8 on page 7: Test information has been added. 			
BLS6G2731S-130 v.1	20100726	Objective data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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